

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 247135US0DIV		SERIAL NO. <u>10/743,478</u> <del>New Divisional Application</del>				
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Geoffrey J. DAVIES, et al.						
				FILING DATE HEREWITH <u>12/23/2003</u>		GROUP <u>1722</u>				
U.S. PATENT DOCUMENTS										
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE			
<u>ST</u>	AA	4,551,316	11/85	Iizuka	<u>7</u>	<u>7</u>				
	AB	5,151,107	09/92	Cho et al.						
	AC	6,270,548	08/01	Campbell et al.						
	AD	6,576,211	06/03	Davies et al.	<u>2</u>	<u>1</u>				
	AE									
	AF									
	AG									
	AH									
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	AK									
	AL									
	AM									
	AN									
	FOREIGN PATENT DOCUMENTS									
			DOCUMENT NUMBER	DATE			COUNTRY	TRANSLATION		
					YES	NO				
<u>ST</u>	AO	0079117	05/83	Europe						
	AP									
	AQ									
	AR									
	AS									
	AT									
	AU									
	AV									
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)										
<u>ST</u>	AW	Hongchang YU et al.; "Sintering of Ultrafine Diamond Particles Under High Temperature and High Pressure"; Diamond and Related Materials, Vol. 3, No. 3, pp. 222-226; 02/01/94								
	AX	Shi Ming HONG et al.; "Diamond Formation from a System of SiC and a Metal"; Diamond and Related Materials, Vol. 2, pp. 508-511; 1993								
	AY	Jae-Kap LEE et al.; "Effect of the Bucyancy Force on Diamond Formation During Synthesis Under a High Pressure"; Vol. 2, pp. 469-499; 03/01/93								
	AZ	A.V. ANDREYEV et al.; "Diamond Formation and Wettability in a Mg-Cu-C System Under High Pressure and High Temperature"; Vol. 6, No. 1, pp. 28-32; 01/1997				<input type="checkbox"/> Additional References sheet(s) attached				
Examiner <u>[Signature]</u>										
				Date Considered <u>5/05</u>						
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.										